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ABSTRACT OF THE DISCLOSURE

a  
a 5 A semiconductor chip 2 is disposed within a  
device hole as formed in a tape base material 1a of a  
tape carrier 1, which chip is <sup>smaller</sup> ~~less~~ in thickness than  
the tape base material 1a, <sup>and then</sup> ~~while~~ <sup>is performed using</sup> sealing ~~by~~ a seal  
resin 3 to permit both the principal surface and back  
surface of such semiconductor chip 2 to be coated  
therewith. And, ~~let~~ the position of the semiconductor  
chip 2 in a direction along the thickness of the tape  
base 1a <sup>is set to correspond</sup> ~~be identical~~ to a stress neutral plane of the  
TCP as a whole.